

SMD Comm COG, Ceramic, 330 pF, 5%, 50 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 0805



Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
T	0.78mm +/-0.10mm
S	0.75mm MIN
B	0.5mm +/-0.25mm

Packaging Specifications	
Packaging:	T&R, 330mm, Paper Tape
Packaging Quantity:	15000

General Information	
Series:	SMD Comm COG
Style:	SMD Chip
Description:	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features:	Ultra-Stable, Low Loss, Class I
RoHS:	Yes
Termination:	Tin
Marking:	No
AEC-Q200:	No
Component Weight:	11 mg
Shelf Life:	78 Weeks
MSL:	1

Specifications	
Capacitance:	330 pF
Measurement Condition:	1 MHz 1.0Vrms
Capacitance Tolerance:	5%
Voltage DC:	50 VDC
Dielectric Withstanding Voltage:	125 VDC
Temperature Range:	-55/+125°C
Temperature Coefficient:	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC):	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor:	0.1% 1 MHz 1.0Vrms
Aging Rate:	0% Loss/Decade Hour
Insulation Resistance:	100 GOhms

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